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(74) Agents: **AOKI, Atsushi** et al.; A. Aoki, Ishida & Associates, Toranomon 37 Mori Bldg., 5-1, Toranomon 3-chome, Minato-ku, Tokyo 1058423 (JP).

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(71) Applicant (*for all designated States except US*): **SHOWA DENKO K.K.** [JP/JP]; 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 1058518 (JP).

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **KANEDA, Masato** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP). **MIKAWA, Yasuhiro** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP). **SHIMIZU, Koji** [JP/JP]; C/o Showa Denko K.K., 4980, Kaiseicho, Shunan-shi, Yamaguchi 7460006 (JP).

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(54) Title: PHOTSENSITIVE COMPOSITION REMOVER

(57) Abstract: A photosensitive composition remover used for removal of an uncured photosensitive composition, which remover comprises 1 to 80 percent by mass of at least one type of aromatic hydrocarbon having 9 carbon atoms or more within the molecule. The photosensitive composition remover further comprises an aprotic polar solvent and/or another solvent other than aprotic polar solvents. The photosensitive composition remover is effective for removal of an uncured photosensitive composition film deposited at the periphery, edges, or back of a substrate or removal of an uncured photosensitive composition deposited at the surface of system members or equipment in a process for forming a photosensitive composition film on a glass substrate, a semiconductor wafer, or the like. It is preferably used for removal of a photosensitive composition containing a pigment in a process for forming a photosensitive composition film on a substrate in the process of production of a liquid crystal or an organic EL display.



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